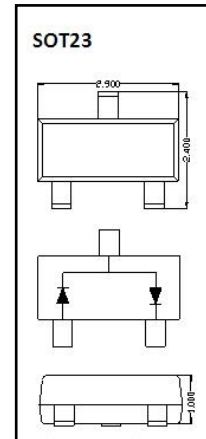


DATA SHEET

MMBD7000

- ◇ Fast Switching Speed
- ◇ For General Purpose Switching Applications
- ◇ High Conductance
- ◇ Low Current Leakage
- ◇ Small Outline Surface Mount Package
- ◇ RoHS compliant / Green EMC

Device Marking Code	
MMBD7000	M5C



MAXIMUM RATINGS (Ta = 25 °C)

Symbol	Parameter	Value	Units
V_R	Reverse Voltage	100	V
V_R (RMS)	RMS Reverse Voltage	53	V
I_o	Average Rectified Output Current	200	mA
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	556	°C/W
I_{FSM}	Peak Forward Surge Current t=1s, Non-Repetitive	0.5	A
P_D	Power Dissipation	225	mW
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (Ta = 25 °C)

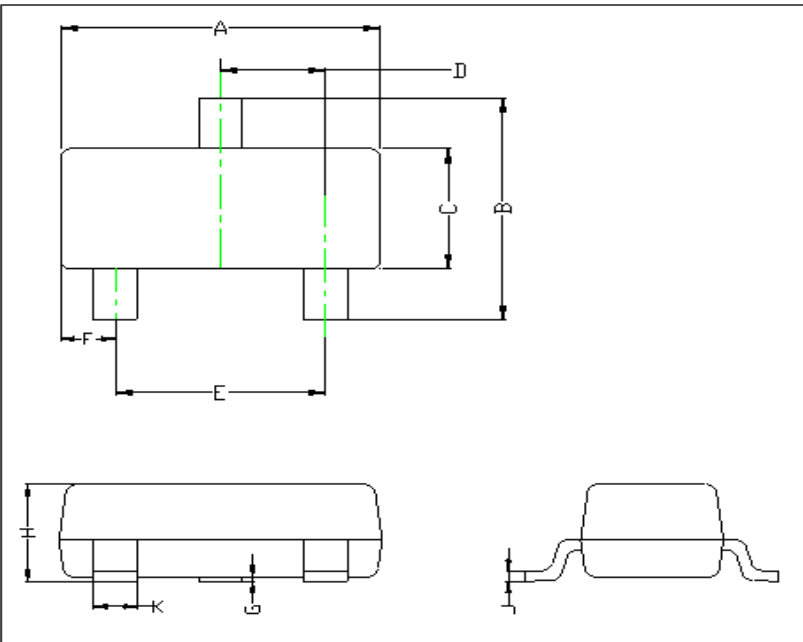
Symbol	Parameter	Test Conditions	Min	Max	Units
V_F	Forward Voltage	$I_F=10mA$		0.855	V
		$I_F=100mA$		1.1	V
V_R	Reverse breakdown voltage	$I_R=100\mu A$	100		V
I_R	Reverse voltage leakage current	$V_R=50V T_j=25^\circ C$		1.0	uA
		$V_R=50V T_j=125^\circ C$		100	
		$V_R=100V$		3.0	
C_T	Capacitance between terminals	$V_R=0V, f=1MHz$		2	pF
T_{rr}	Reverse recovery time	$I_F=I_R=10mA$ $I_{rr}=0.1 \times I_R, R_L=100\Omega$		4	nS

ORDERING INFORMATION

Device	Package	Shipping	Tape wide	Emboss pitch	Tape specification	Notes
MMBD7000	SOT23	Tape & Reel 3000pcs /7" Reel	8mm	4mm	Conductive	

PACKAGE DIMENSIONS

Package Outline : SOT23



Symbol	Dimensions in mm	
	Min.	Max.
A	2.800	3.040
B	2.100	2.640
C	1.200	1.400
D	0.890	1.030
E	1.780	2.050
F	0.450	0.600
G	0.013	0.100
H	0.900	1.110
J	0.090	0.180
K	0.370	0.510

SOT23 Package Outline

Note:
 1. Halogen free ,EMC
 2. Pb free solder
 3. Lead thickness solder plating
 4. Lead frame CAC-5
 5. Other Tolerance ± 0.05
 6. Dimensions are exclusive of Burrs Mold Flash and Tie Bar extrusions
 7. Unit :mm

NOTICE

AM'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS COMPONENTS IN ANY LIFE SUPPORT DEVICES OR SYSTEMS.

AM reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. AM does not assume any liability arising out of the application or use of any product described herein.